# Gap Pad<sup>®</sup> 2500

Thermally Conductive, Un-Reinforced Gap Filling Material

#### **Features and Benefits**

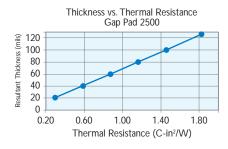
- Thermal conductivity: 2.7 W/m-K
- High thermal performance, cost-effective solution
- · Un-reinforced construction for additional compliancy
- · Medium compliancy and conformability



Gap Pad 2500 is a thermally conductive, electrically insulating, un-reinforced gap filling material. Gap Pad 2500 is a filled-polymer material yielding an elastic polymer that allows for easy handling and converting without the need for reinforcement. These properties also allow for good wet-out and interfacing characteristics to surfaces with roughness and/or topography. All these characteristics make this material ideal for applications using either clip or screw-mounted assemblies.

Gap Pad 2500 is offered with inherent natural tack on both sides of the material allowing for stick-in-place characteristics during application assembly. The material is supplied with protective liners on both sides.

Note: Resultant thickness is defined as the final gap thickness of the application.



#### TYPICAL PROPERTIES OF GAP PAD 2500 PROPERTY IMPERIAL VALUE METRIC VALUE TEST METHOD Light Brown Light Brown Visual Reinforcement Carrier Thickness (inch) / (mm) 0.020 to 0.125 0.508 to 3.175 ASTM D374 Inherent Surface Tack (1- or 2-sided) Density (g/cc) 31 31 ASTM D792 Heat Capacity (J/g-K) 1.0 1.0 ASTM E1269 Hardness, Bulk Rubber (Shore 00) (1) 80 80 ASTM D2240 779 ASTM D575 Young's Modulus (psi) / (kPa) (2) 113 Continuous Use Temp (°F) / (°C) -76 to 392 -60 to 200 **ELECTRICAL** Dielectric Breakdown Voltage (Vac) >6000 >6000 ASTM D149 Dielectric Constant (1000 Hz) 6.8 6.8 ASTM D150 Volume Resistivity (Ohm-meter) 101 101 ASTM D257 Flame Rating V-O V-O U.L. 94 THERMAL Thermal Conductivity (W/m-K) 2.7 2.7 **ASTM D5470**

- 1) Thirty second delay value Shore 00 hardness scale.
  2) Young's Modulus, calculated using 0.01 in/min. step rate of strain with a sample size of 0.79 inch². For more information on Gap Pad modulus, refer to Bergquist Application Note #116.

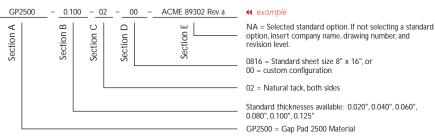
### Typical Applications Include:

- Multiple heat-generating components to a common heat sink
- · Graphics chips to heat sinks
- · Processors to heat sinks
- Mass storage drives
- Wireline / wireless communications hardware

## **Configurations Available:**

• Sheet form and die-cut parts

### **Building a Part Number**



Note: To build a part number, visit our website at www.bergquistcompany.com

Gap Pad®: U.S. Patent 5,679,457 and others



www.bergquistcompany.com

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**Standard Options**